

Part Number: XZ46WHT-9AC34

SUBMINIATURE SOLID STATE LAMP

Features

- High reliability LED package.
- Ideal for indication light on hand held products
- Standard Package: 1,000pcs/ Reel
- \bullet MSL (Moisture Sensitivity Level): 3
- RoHS compliant



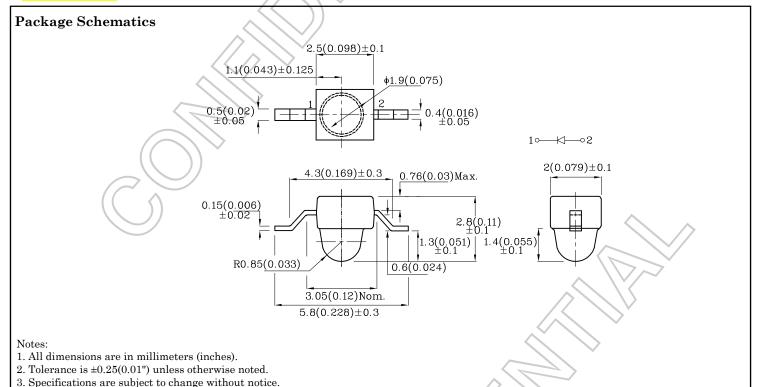




ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES

Applications

- Backlighting for tell-tale indicators
- Dashboard lighting
- Interior lighting (footwell, dome light, accent lighting, etc.)
- Exterior lighting (turn signals, side markers, CHMSL, etc.)
- Signs and signals
- Various applications requiring high temperature rating



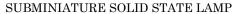
Part Number	Emitting Color (Material)	Lens-color		minous Inten CIE127-2007 IF=20mA) mc	k	Viewing Angle 20 1/2
		<u> </u>	Code.	Min.	Max.	
		\wedge	W*	1600*	1900*	
			X*	1900*	2300*	
			Y*	2300*	2700*	
XZ46WHT-9AC34	Yellow (AlGaInP)	Water Clear	Z*	2700*	3100*	20°
			ZA*	3100*	3600*	
			ZB*	3600*	4200*	
			ZC*	4200*	5000*	

Notes

- 1.01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
- 2. Luminous intensity / luminous Flux: +/-15%.
- * Luminous intensity value and wavelength are in accordance with CIE127-2007 standards. Mar 03,2018



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Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Value	Unit
Power dissipation	PD	75	mW
Junction temperature	T_J	5	$^{\circ}\mathrm{C}$
Reverse Voltage	$V_{ m R}$	115	V
Operating Temperature	Тор	-40 To +100	°C
Storage Temperature	Tstg	-40 To +115	°C
DC Forward Current [1]	Ir	30	mA
Peak Forward Current [2]	IFM	175	mA
Electrostatic Discharge Threshold (HBM)		3000	V
Thermal Resistance (Junction/ambient) [1]	Rth/j-a	330	°C/W
Thermal Resistance (Junction/ambient) [1]	Rth j-S	175	°C/W

Notes:

- 1. Rth(j-a) Results from mounting on PC board FR4 (pad size≥16 mm² per pad),
- 2. 1/10 Duty Cycle, 0.1ms Pulse Width.
- 3.A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

Electrical / Optical Characteristics at Ta=25°C

Parameter	Symbol	Value				Unit
rarameter		Code.	Min.	Тур.	Max.	Onit
Wavelength at peak emission CIE127-2007* IF = 20mA	λ peak	-	-	590*		nm
	λ dom ^{[1}]	3*	586*	//-	588*	
Dominant Wavelength CIE127-2007*		4*	588*		590*	
$I_F = 20 \text{mA}$		5*	590*		592*	nm
		6*	592*	1).	594*	
Reverse Current (VR = 5V)	Ir	- //		10	-	uA
Spectral bandwidth at 50% Frel Max If = $20mA$	Δλ		\ <u>\</u>	20	-	nm
Forward Voltage I _F = 20mA	V _F [2]) -	2	2.5	V
Temperature coefficient of $\lambda peak$ If = 20mA, -10°C \leq T \leq 100°C	$\mathrm{TC}_{\mathrm{lpeak}}$		-	0.12	-	nm/°C
Temperature coefficient of λdom IF = 20mA, -10°C \leq T \leq 100°C	$\mathrm{TC}_{\mathrm{ldom}}$	-	-	0.07	-	nm/°C
Temperature coefficient of VF $I_F = 20 mA, -10 {\rm ^{\circ}C} \leq T \leq 100 {\rm ^{\circ}C}$	TCv	-	-	-1.9	-	mV/°C

Notes:

- 1. Wavelength: +/-1nm.
- 2. Forward Voltage: +/-0.1V.
- * Wavelength value is in accordance with CIE127-2007 standards.

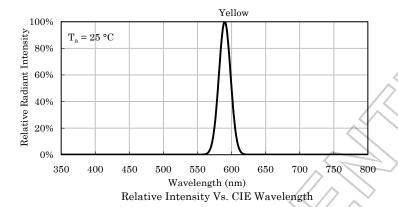
Mar 03,2018

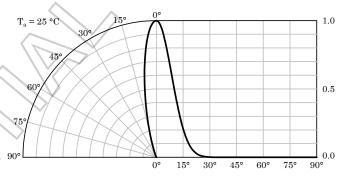
XDSB9097 V1-Z Layout: Maggie L.



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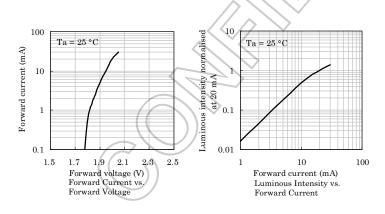


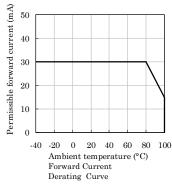


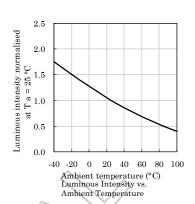


Spatial Distribution

❖ Yellow

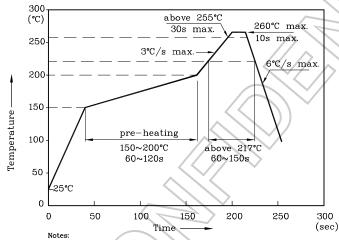






LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)



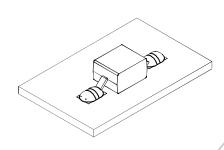
- 1. All temperatures refer to the center of the package,
- measured on the package body surface facing up during reflow.

 2. Do not apply any stress to the LED during high temperature conditions.

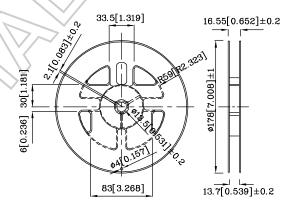
 3. Maximum number of soldering passes: 2



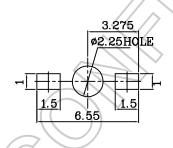
❖ The device has a single mounting surface. The device must be mounted according to the specifications.

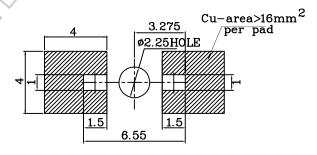


Reel Dimension



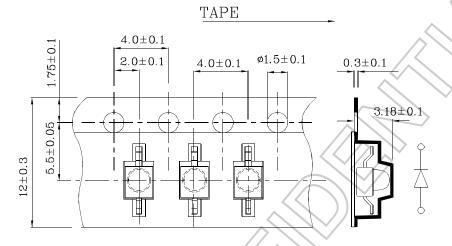
❖ Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)





Solder resist

* Tape Specification (Units: mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

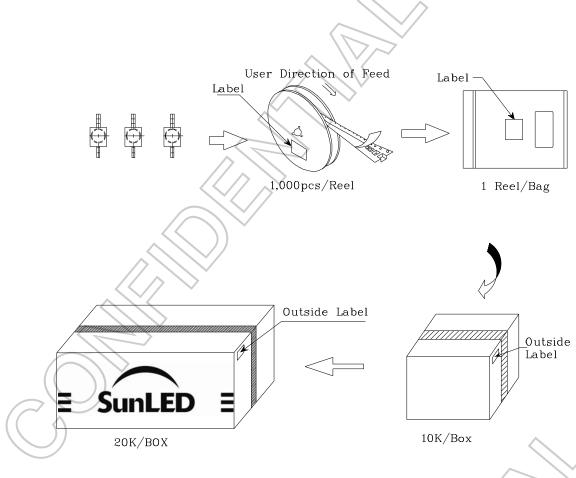
- 1. Wavelength: +/-1nm
- 2. Luminous intensity / luminous flux: +/-15%
- 3. Forward Voltage: +/-0.1V

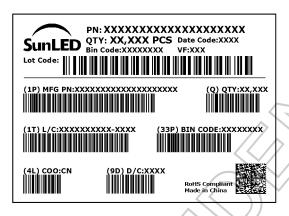
Note: Accuracy may depend on the sorting parameters





PACKING & LABEL SPECIFICATIONS





TERMS OF USE

- 1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet. User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
- 4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
- 5. The contents within this document may not be altered without prior consent by SunLED.
- 6. Additional technical notes are available at http://www.SunLEDusa.com/TechnicalNotes.asp

Mar 03,2018

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Reliability Test Items And Conditions

The reliability of products shall be satisfied with items listed below

Lot Tolerance Percent Defective (LTPD): 10%

No.	Test Item	Standards	Test Condition	Test Times / Cycles	Number of Damaged
1	Continuous operating test		T_a = 25°C, I_F = maximum rated current *	1,000 h	0 / 22
2	High Temp. operating test	EIAJ ED-4701/100 (101)	T_a = 100°C, I_F = maximum rated current *	1,000 h	0 / 22
3	Low Temp. operating test		T_a = -40°C, I_F = maximum rated current *	1,000 h	0 / 22
4	High temp. storage test	EIAJ ED-4701/100 (201)	T_a = maximum rated storage temperature	1,000 h	0 / 22
5	Low temp. storage test	EIAJ ED-4701/100 (202)	Ta = -40°C	1,000 h	0 / 22
6	High temp. & humidity storage test	EIAJ ED-4701/100 (103)	$T_a = 60$ °C, RH = 90%	1,000 h	0 / 22
7	High temp. & humidity operating test	EIAJ ED-4701/100 (102)	T_a = 60°C, RH = 90% I_F = maximum rated current *	1,000 h	0 / 22
8	Soldering reliability test	EIAJ ED-4701/100 (301)	Moisture soak: 30°C, 70% RH, 72h Preheat: 150~180°C (120s max.) Soldering temp: 260°C(10s)	2 times	0 / 18
9	Thermal shock operating test	-	T_a = -40°C(15min) ~ 100°C(15min) I_F = derated current at 100°C	1,000 cycles	0 / 22
10	Thermal shock test	-	T_a = -40°C(15min) ~ maximum rated Storage temperature(15min)	1,000 cycles	0 / 22
11	Electric Static Discharge (ESD)	EIAJ ED-4701/100 (304)	$C = 100 pF, R2 = 1.5 K\Omega V = 3000 V$	Once each Polarity	0 / 22
12	Vibration test	-	$a = 196 \text{m/s}^2$, $f = 100 \sim 2 \text{KHz}$, $t = 48 \text{min for all}$ xyz axes	4 times	0 / 22

 $[\]mbox{\ensuremath{\star}}$: Refer to forward current vs. derating curve diagram

Criteria for Judging Damage

Items	Symbols	Conditions	Failure Criteria			
luminous Intensity	lv	IF = 20mA	Testing Min. Value <spec.min.value 0.5<="" td="" x=""></spec.min.value>			
Forward Voltage	VF	IF = 20mA	Testing Max. Value ≥Spec.Max.Value x 1.2			
Reverse Current	IR	VR = Maximum Rated Reverse Voltage	Testing Max. Value ≥Spec.Max.Value x 2.5			
High temp. storage test	-		Occurrence of notable decoloration, deformation and cracking			

Mar 03,2018 XDSB9097 V1-Z Layout: Maggie L.